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TI Fine copper alloy wire with high strength and flexibility  
PA Furukawa Electric Co., Ltd., Japan  
SO Jpn. Kokai Tokkyo Koho, 4 pp.  
CODEN: JKXXAF  
DT Patent  
LA Japanese

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AB The Cu alloys contain Sn 0.1-1, Ag 0.1-0.49, and optionally P, Zn, and/or Mn  $\leq 0.2\%$ . An ingot is scalped, hot worked, annealed at 550°, pickled, drawn 99.96% to 0.15 mm, and straightened. The yield strength is 77.2-80.3, tensile strength 87.9-89.7 kg/mm<sup>2</sup>, elec. conductivity 64.8-84.7% IACS, flexibility good, and drawability satisfactory, compared with 72.1, 74.3 kg/mm<sup>2</sup>, 30.8% , bad, and difficult to 89.8% for the conventional Cu alloy containing Ni 1.98 and Mn 0.48%. A typical Cu alloy [84506-98-9] contains Sn 0.11 and Ag 0.49%.